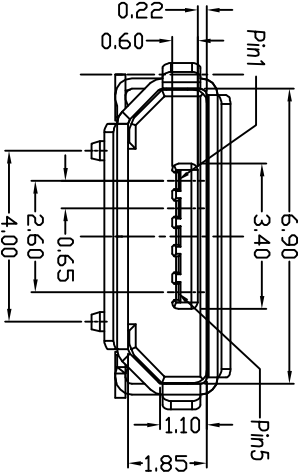
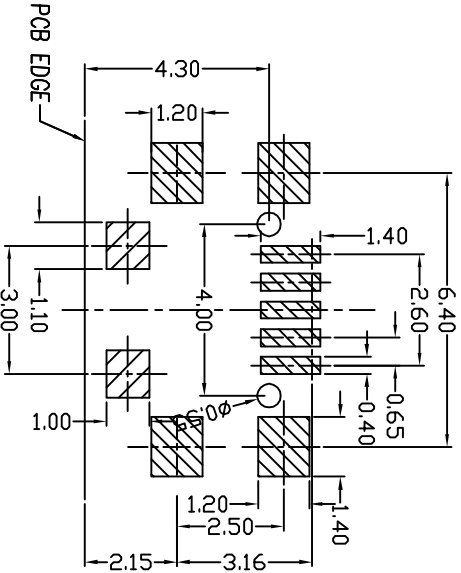
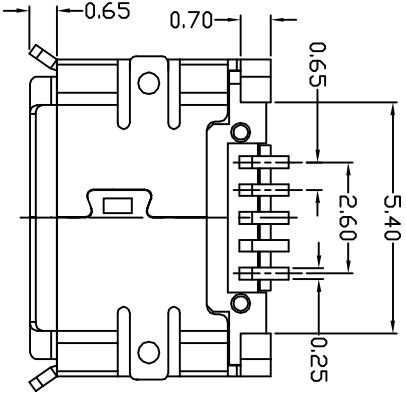
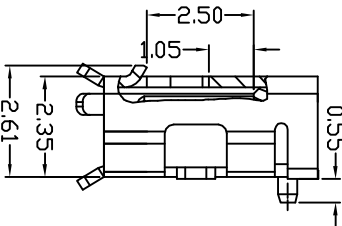
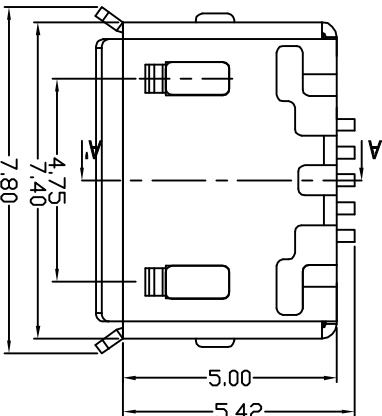
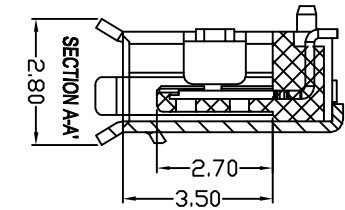
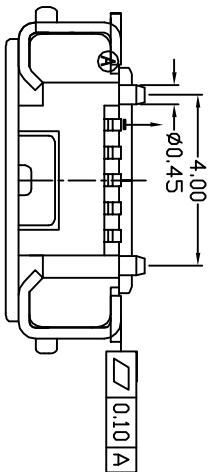


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



Notes:

1. Materials:

- 1.1 Housing: High temperature thermoplastic with g.f.U.L94 v-0.
- 1.2 Contact: copper alloy,t=0.20mm ,NI 50U",Gold 1U".
- 1.3 Shell: copper alloy,t=0.25mm,NI 80U",SN 80U".

2. Specifications:

- 2.1. Current rating: 1 A Max.
- 2.2. Dielectric withstanding:voltage: 100 V(ac) for 1 min.
- 2.3. Contact resistance: 50 mW Max.
- 2.4. Insulation resistance: 100 MW Min.
- 2.5. Total mating force: 3.57 Kgf Max.
- 2.6. Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.after 10000 insertion/extraction cycles
- 2.7. Temperature range: -30°C~+80°C

PART NO: 1-MD05SMXXX-01				MATERIAL: SEE NOTE	
MODEL NO:				FINSH: SEE NOTE	
UNIT: mm		SIZE: A4		COLOR: SEE NOTE	
TOLERANCE UNSPECIFIED				DR: ?/?/?	
2 Shell		1 1		N/A	
2 Contact		5 5		N/A	
1 Housing		1 1		N/A	
No. Name		Q'ty		Finish	

TITLE: Micro usb 99-B-type (四脚全贴) 有孔型			
DWG NO: SHK-20153		REV: A	
CHK: .xx ±0.38		APP: .xxx ±0.25	
SCALE: 1:1		SHEET: 1/1	

REV: A			
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深圳市顺宏康科技有限公司

RECOMMENDED PCB LAYOUT

深圳市顺宏康科技有限公司